

Title of Change:	ON Semiconductor Seremban Malaysia Factory added for Saw and T&R Operations on the NCP6925 family of devices and backside laminate option added to the NCP6925B.		
Proposed first ship date:	17 May 2017 or earlier after customer approval		
Contact information:	Contact your local ON Semiconductor Sales Office or <mat.hilton@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office or <Vincent.liu@onsemi.com>		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	Saw and T&R operations will be performed at ON Semiconductor Seremban Malaysia factory as well as at Deca Technologies which is already approved. The only noticeable difference to the end customer will be the label on each reel which will identify whether the die were processed in the ON Semiconductor factory in Seremban Malaysia (ASSY IN: MALAYSIA) or at Deca Technologies in the Philippines (ASSY IN: PHILIPPINES). NCP6925B die with backside laminate will be assigned a new part number which is NCP6925BFCCT2G. The part number for die without backside laminate will remain as NCP6925BFCT2G. The laser marking will remain as "6925B" for both part numbers so the only way to physically differentiate between the 2 part numbers will be whether backside laminate exists on the die.		
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☒ Other: <u>T&R</u>		
Change Sub-Category(s):	☒ Manufacturing Site Change/Addition ☒ Material Change ☐ Datasheet/Product Doc change ☒ Manufacturing Process Change ☐ Product specific change ☒ Shipping/Packaging/Marking ☐ Other: _____		
Sites Affected:	☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : <u>ON Seremban, Malaysia</u> ☒ External Foundry/Subcon site(s) : <u>Deca Technologies</u>		
Description and Purpose:			
This is the final notification announcing that ON Semiconductor is incorporating the following 2 changes:			
- ON Semiconductor Seremban Malaysia factory is being added as a second source for wafer saw and tape & reel for the NCP6925 family of devices. There are no physical or electrical changes to the die including the laser marking which will remain as "6925A" or "6925B". - Backside laminate is being added as an option to the NCP6925B family. The NCP6925B will now be available with or without backside laminate. Backside laminate will be applied at Deca. The addition of backside laminate includes the following 2 changes: - The die is background from 360 um for the non-laminate version to 338 um for the laminate version. - A 22 um thick laminate is added to the backside of the die. The total die thickness remains at 360 um. There are no additional physical or electrical changes to the die including the laser marking which will remain as "6925A" or "6925B".			



Reliability Data Summary: N/A

Electrical Characteristic Summary: N/A

List of affected Standard Parts:

Part Number	Seremban Saw and T&R	Backside Laminate
NCP6925AFCT2G	Yes	No
NCP6925AFCT1G	Yes	No
NCP6925AFCCT1G	Yes	Yes
NCP6925BFCT2G	Yes	No
NCP6925BFCCT2G	Yes	Yes